

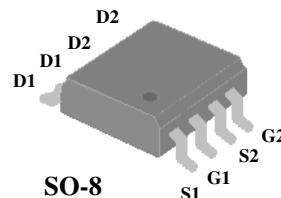
**AP9960GM-HF**  
**Halogen-Free Product**



**Advanced Power  
Electronics Corp.**

*N-CHANNEL ENHANCEMENT MODE  
POWER MOSFET*

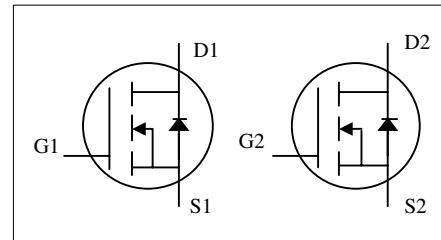
- ▼ Low On-Resistance
- ▼ Fast Switching Speed
- ▼ Surface Mount Package
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	40V
$R_{DS(ON)}$	20mΩ
$I_D$	7.8A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current <sup>3</sup>	7.8	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current <sup>3</sup>	6.2	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	20	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	2	W
	Linear Derating Factor	0.016	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-amb}$	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	62.5	°C/W



## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	40	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	0.032	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=7\text{A}$	-	-	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=5\text{A}$	-	-	32	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	1	-	3	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=7\text{A}$	-	25	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	1	$\text{uA}$
	Drain-Source Leakage Current ( $T_j=70^\circ\text{C}$ )	$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	25	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	$\text{nA}$
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=7\text{A}$	-	14.7	-	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=20\text{V}$	-	7.1	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=4.5\text{V}$	-	6.8	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=20\text{V}$	-	11.5	-	ns
$t_r$	Rise Time	$I_{\text{D}}=1\text{A}$	-	6.3	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=3.3\Omega$ , $V_{\text{GS}}=10\text{V}$	-	28.2	-	ns
$t_f$	Fall Time	$R_D=20\Omega$	-	12.6	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	1725	-	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	235	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	145	-	pF

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$I_S$	Continuous Source Current ( Body Diode )	$V_D=V_G=0\text{V}$ , $V_S=1.3\text{V}$	-	-	1.54	A
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$T_j=25^\circ\text{C}$ , $I_S=2.3\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.3	V

## Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board ;  $135^\circ\text{C}/\text{W}$  when mounted on Min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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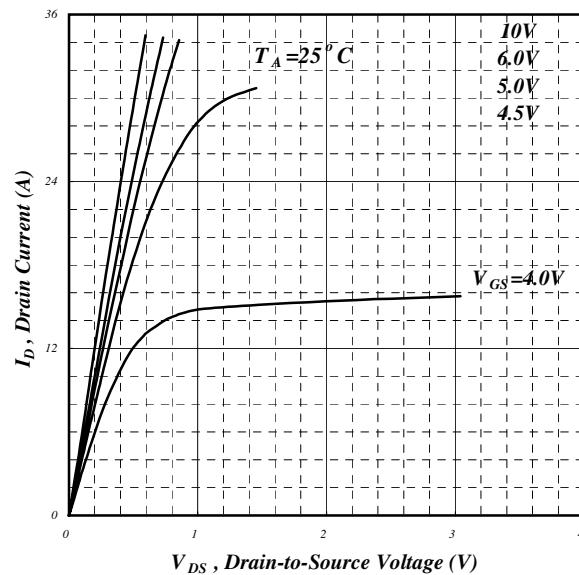


Fig 1. Typical Output Characteristics

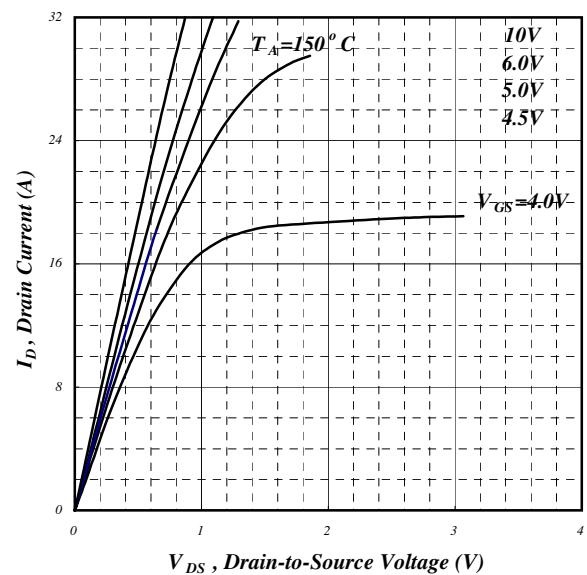


Fig 2. Typical Output Characteristics

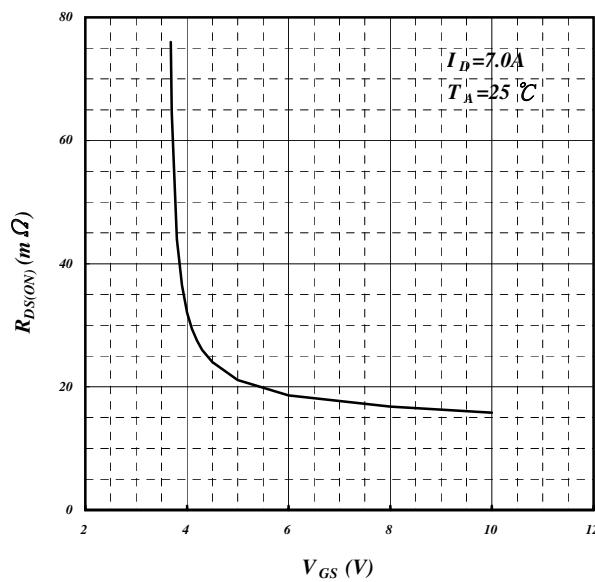


Fig 3. On-Resistance v.s. Gate Voltage

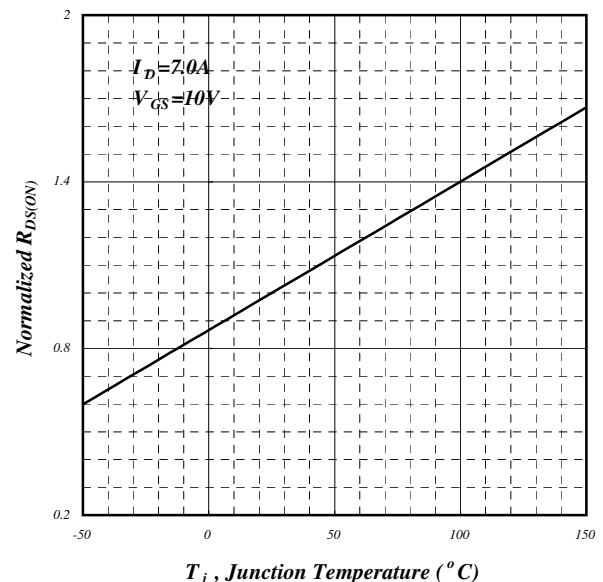
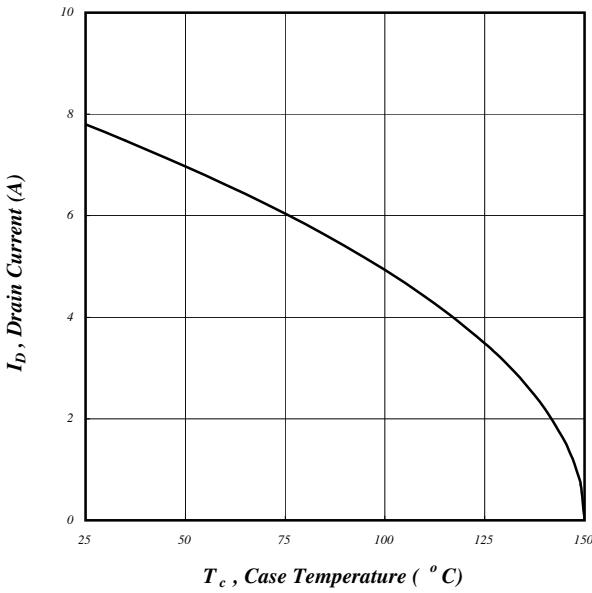
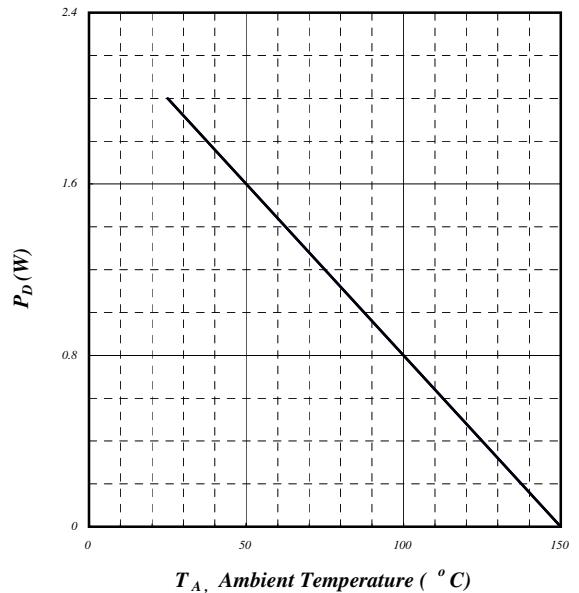


Fig 4. Normalized On-Resistance v.s. Junction Temperature

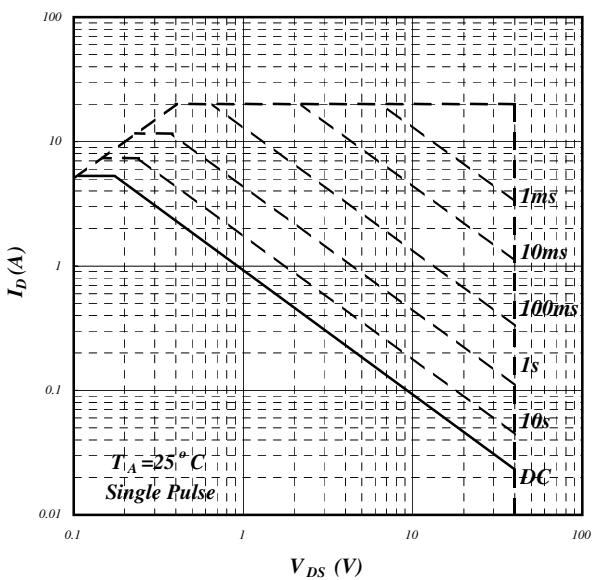
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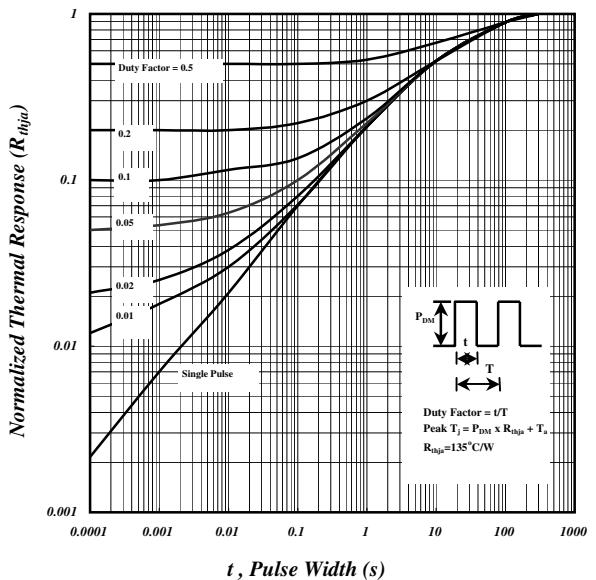
**Fig 5. Maximum Drain Current v.s.  
Case Temperature**



**Fig 6. Typical Power Dissipation**



**Fig 7. Maximum Safe Operating Area**



**Fig 8. Effective Transient Thermal Impedance**

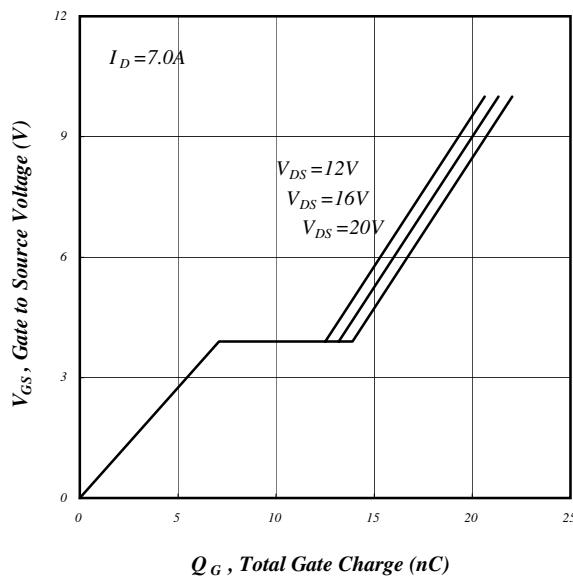


Fig 9. Gate Charge Characteristics

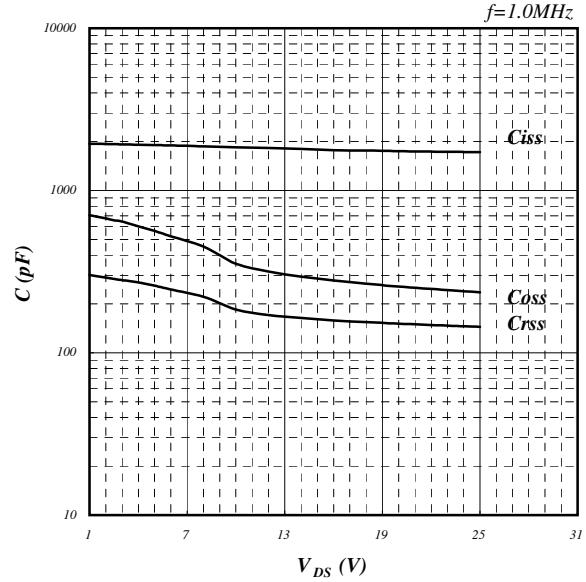


Fig 10. Typical Capacitance Characteristics

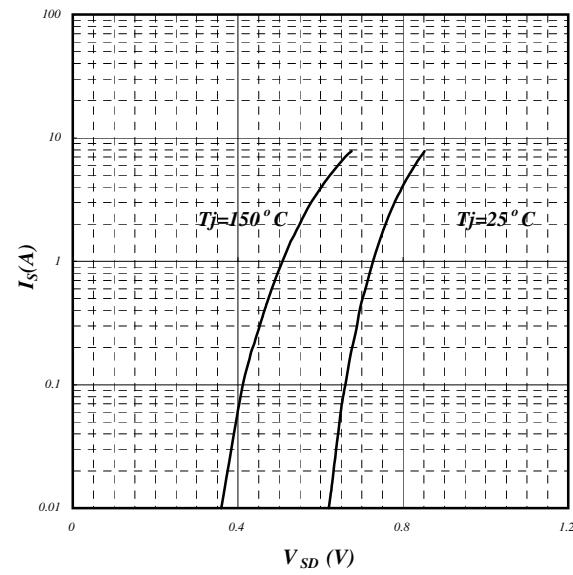


Fig 11. Forward Characteristic of Reverse Diode

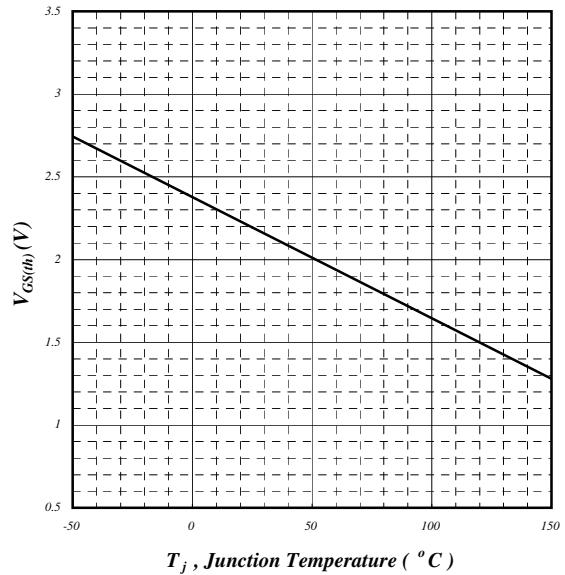


Fig 12. Gate Threshold Voltage v.s. Junction Temperature



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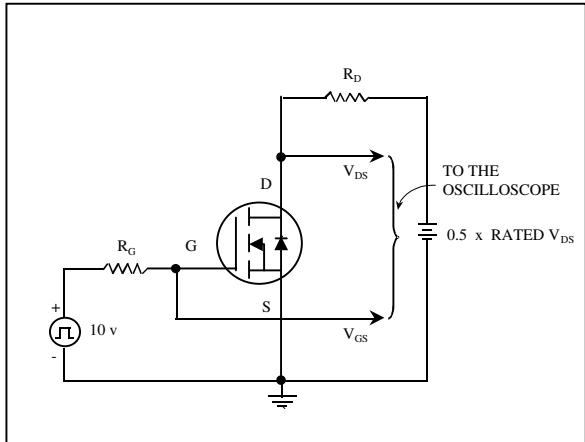


Fig 13. Switching Time Circuit

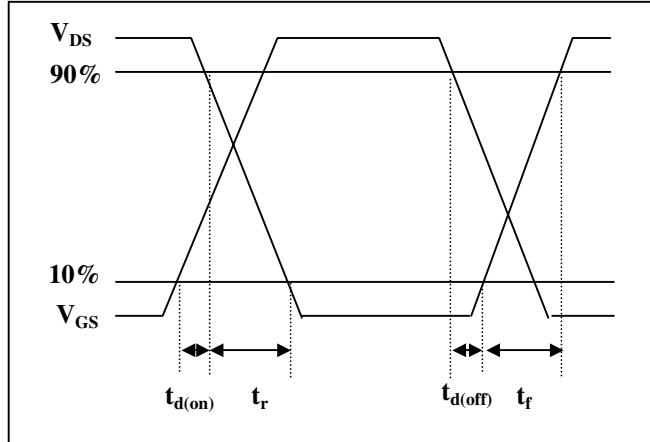


Fig 14. Switching Time Waveform

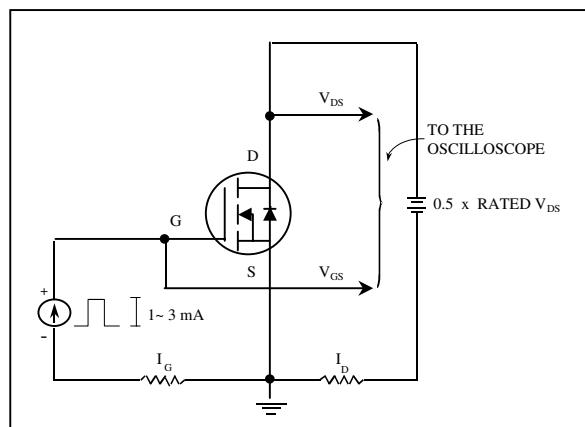


Fig 15. Gate Charge Circuit

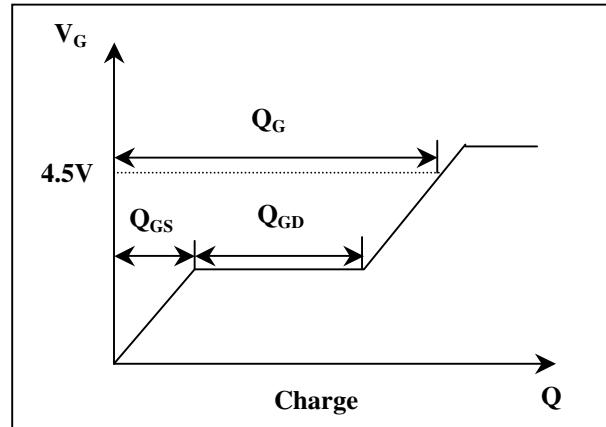


Fig 16. Gate Charge Waveform